



## 6.5A, 200V, 0.800 Ohm, P-Channel Power MOSFETs

These are P-Channel enhancement mode silicon gate power field effect transistors. They are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for other high-power switching devices. The high input impedance allows these types to be operated directly from integrated circuits.

Formerly developmental type TA17512.

### Ordering Information

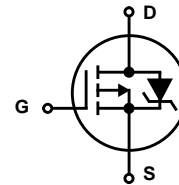
PART NUMBER	PACKAGE	BRAND
IRF9630	TO-220AB	IRF9630
RF1S9630SM	TO-263AB	RF1S9630

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-263AB variant in the tape and reel, i.e., RF1S9630SM9A.

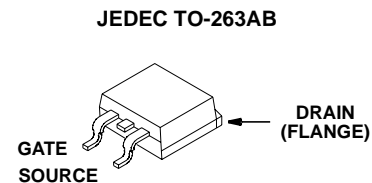
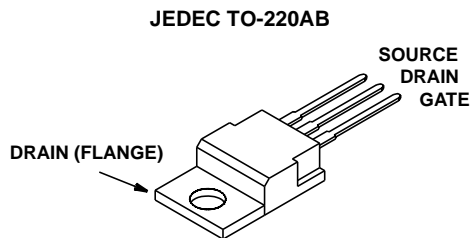
### Features

- 6.5A, 200V
- $r_{DS(ON)} = 0.800\Omega$
- Single Pulse Avalanche Energy Rated
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

### Symbol



### Packaging



# IRF9630, RF1S9630SM

## Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

	IRF9630, RF1S9630SM	UNITS
Drain to Source Voltage (Note 1) . . . . .	$V_{DS}$	V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1) . . . . .	$V_{DGR}$	V
Continuous Drain Current . . . . .	$I_D$	A
$T_C = 100^\circ\text{C}$ . . . . .	$I_D$	A
Pulsed Drain Current (Note 3) . . . . .	$I_{DM}$	A
Gate to Source Voltage . . . . .	$V_{GS}$	V
Maximum Power Dissipation . . . . .	$P_D$	W
Dissipation Derating Factor . . . . .	0.6	$W/^\circ\text{C}$
Single Pulse Avalanche Energy Rating (Note 4) . . . . .	$E_{AS}$	mJ
Operating and Storage Temperature . . . . .	$T_J, T_{STG}$	$^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s . . . . .	$T_L$	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334 . . . . .	$T_{pkg}$	$^\circ\text{C}$

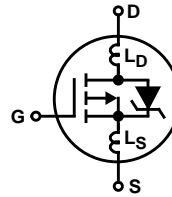
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

1.  $T_J = 25^\circ\text{C}$  to  $125^\circ\text{C}$

## Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = -250\mu\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 10)	-200	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = -250\mu\text{A}$	-2	-	-4	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = \text{Rated } BV_{DSS}$ , $V_{GS} = 0\text{V}$	-	-	-25	$\mu\text{A}$
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ , $V_{GS} = 0\text{V}$ , $T_C = 125^\circ\text{C}$	-	-	-250	$\mu\text{A}$
On-State Drain Current (Note 2)	$I_{D(ON)}$	$V_{DS} > I_{D(ON)} \times r_{DS(ON)MAX}$ , $V_{GS} = -10\text{V}$	-6.5	-	-	A
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = -3.5\text{A}$ , $V_{GS} = -10\text{V}$ (Figures 8, 9)	-	0.500	0.800	$\Omega$
Forward Transconductance (Note 2)	$g_{fs}$	$V_{DS} \geq I_{D(ON)} \times r_{DS(ON)MAX}$ , $I_D = -3.5\text{A}$ (Figure 12)	2.2	3.5	-	S
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} = -100\text{V}$ , $I_D = -6.5\text{A}$ , $R_G = 50\Omega$	-	30	50	ns
Rise Time	$t_r$	$R_L = 15.4\Omega$ (Figures 17, 18)	-	50	100	ns
Turn-Off Delay Time	$t_{d(off)}$	MOSFET Switching Times are Essentially Independent of Operating Temperature	-	50	100	ns
Fall Time	$t_f$		-	40	80	ns
Total Gate Charge (Gate to Source + Gate to Drain)	$Q_{g(TOT)}$	$V_{GS} = -10\text{V}$ , $I_D = -6.5\text{A}$ , $V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ $I_{g(REF)} = -1.5\text{mA}$ (Figures 14, 19, 20)	-	31	45	nC
Gate to Source Charge	$Q_{gs}$	Gate Charge is Essentially Independent of Operating Temperature	-	18	-	nC
Gate to Drain ("Miller") Charge	$Q_{gd}$		-	13	-	nC
Input Capacitance	$C_{ISS}$	$V_{DS} = -25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$	-	550	-	pF
Output Capacitance	$C_{OSS}$	(Figure 11)	-	170	-	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	50	-	pF
Internal Drain Inductance	$L_D$	Measured From the Contact Screw On Tab To the Center of Die	-	3.5	-	nH
		Measured From the Drain Lead, 6mm (0.25in) From Package to the Center of Die	-	4.5	-	nH
Internal Source Inductance	$L_S$	Measured From the Source Lead, 6mm (0.25in) From Package to Source Bonding Pad	-	7.5	-	nH
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	1.67	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	Typical Socket Mount	-	-	80	$^\circ\text{C/W}$



## Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	$I_{SD}$	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Diode	-	-	-6.5	A
Pulse Source to Drain Current (Note 3)	$I_{SDM}$		-	-	-26	A
Source to Drain Diode Voltage (Note 2)	$V_{SD}$	$T_J = 25^{\circ}\text{C}$ , $I_{SD} = -6.5\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 13)	-	-	-1.5	V
Reverse Recovery Time	$t_{rr}$	$T_J = 150^{\circ}\text{C}$ , $I_{SD} = -6.5\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	400	-	ns
Reverse Recovery Charge	$Q_{RR}$	$T_J = 150^{\circ}\text{C}$ , $I_{SD} = -6.5\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	2.6	-	$\mu\text{C}$

### NOTES:

- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Repetitive Rating: Pulse width limited by Max junction temperature. See Transient Thermal Impedance curve (Figure 3).
- $V_{DD} = 50\text{V}$ , starting  $T_J = 25^{\circ}\text{C}$ ,  $L = 17.75\text{mH}$ ,  $R_G = 25\Omega$ , peak  $I_{AS} = 6.5\text{A}$ . (Figures 15, 16).

## Typical Performance Curves Unless Otherwise Specified

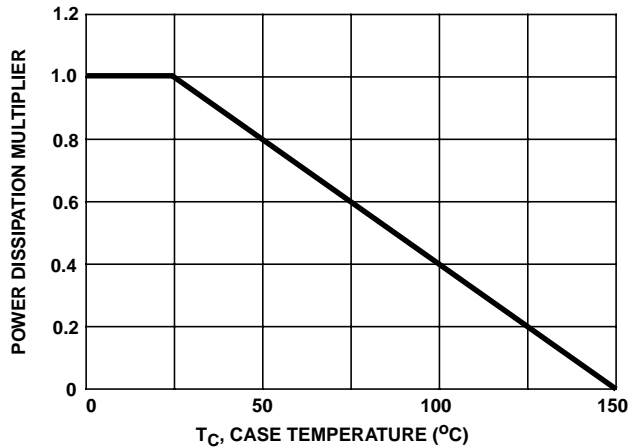


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

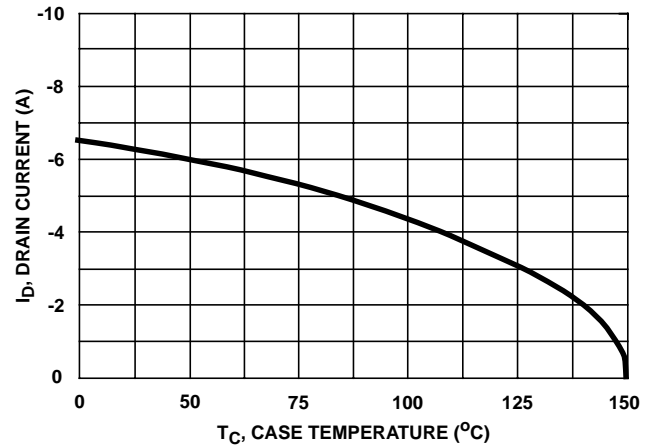


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

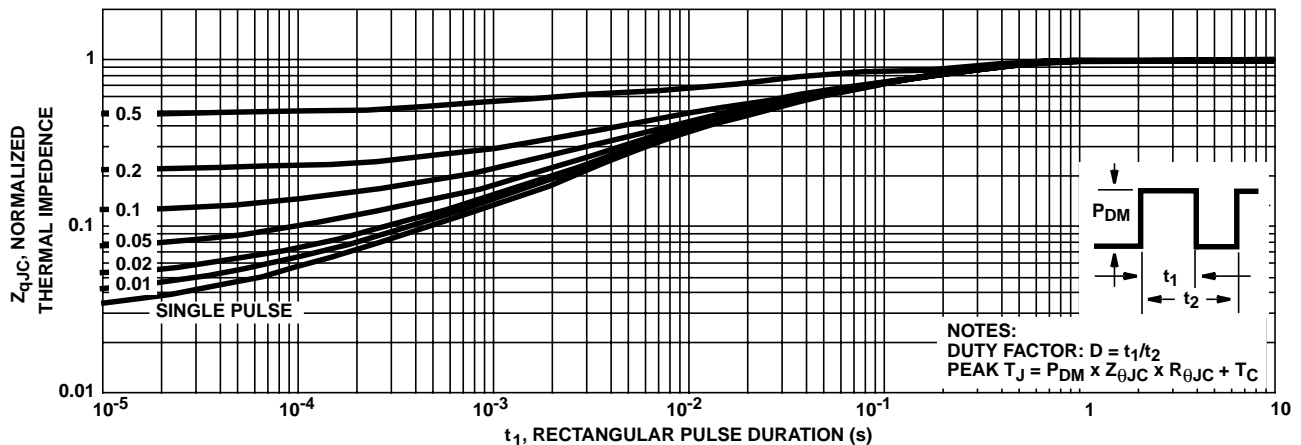


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE